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Details

Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	20
Program Memory Size	768B (512 x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	25 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc55at-04i-so

TABLE 3-1: PINOUT DESCRIPTION - PIC16C54, PIC16CR54, PIC16C56, PIC16CR56, PIC16C58, PIC16CR58

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	DIP	SOIC	SSOP			
RA0	17	17	19	I/O	TTL	Bi-directional I/O port
RA1	18	18	20	I/O	TTL	
RA2	1	1	1	I/O	TTL	
RA3	2	2	2	I/O	TTL	
RB0	6	6	7	I/O	TTL	Bi-directional I/O port
RB1	7	7	8	I/O	TTL	
RB2	8	8	9	I/O	TTL	
RB3	9	9	10	I/O	TTL	
RB4	10	10	11	I/O	TTL	
RB5	11	11	12	I/O	TTL	
RB6	12	12	13	I/O	TTL	
RB7	13	13	14	I/O	TTL	
T0CKI	3	3	3	I	ST	Clock input to Timer0. Must be tied to Vss or VDD, if not in use, to reduce current consumption.
MCLR/VPP	4	4	4	I	ST	Master clear (RESET) input/programming voltage input. This pin is an active low RESET to the device. Voltage on the MCLR/VPP pin must not exceed VDD to avoid unintended entering of Programming mode.
OSC1/CLKIN	16	16	18	I	ST	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	15	15	17	O	—	Oscillator crystal output. Connects to crystal or resonator in crystal Oscillator mode. In RC mode, OSC2 pin outputs CLKOUT, which has 1/4 the frequency of OSC1 and denotes the instruction cycle rate.
VDD	14	14	15,16	P	—	Positive supply for logic and I/O pins.
Vss	5	5	5,6	P	—	Ground reference for logic and I/O pins.

Legend: I = input, O = output, I/O = input/output, P = power, — = Not Used, TTL = TTL input, ST = Schmitt Trigger input

PIC16C5X

FIGURE 5-3: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ NOT TIED TO VDD)

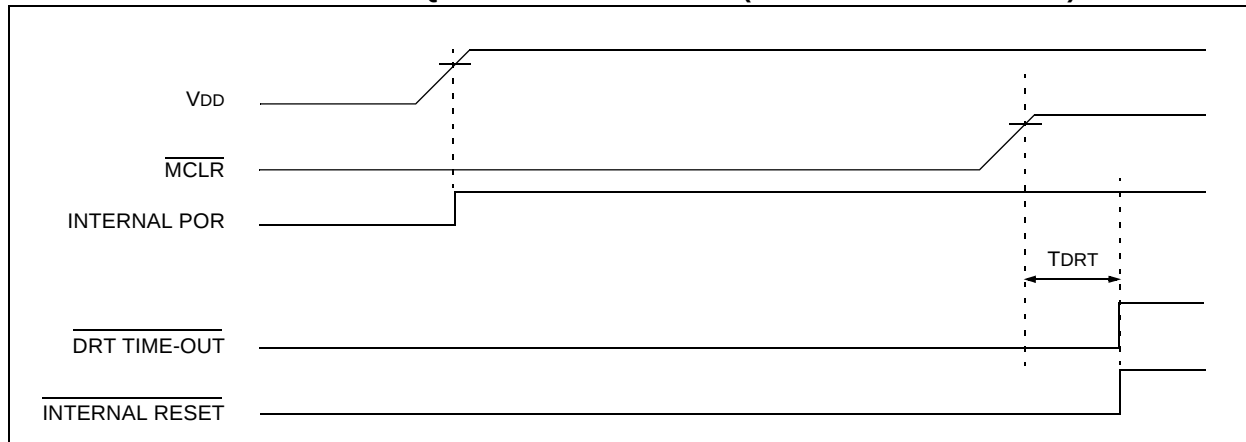


FIGURE 5-4: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ TIED TO VDD): FAST VDD RISE TIME

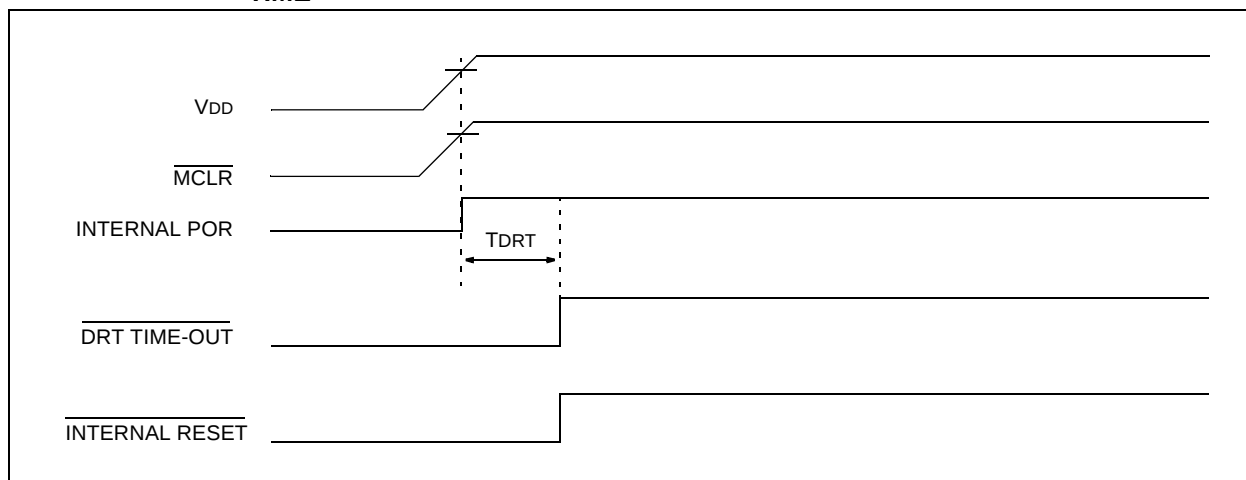
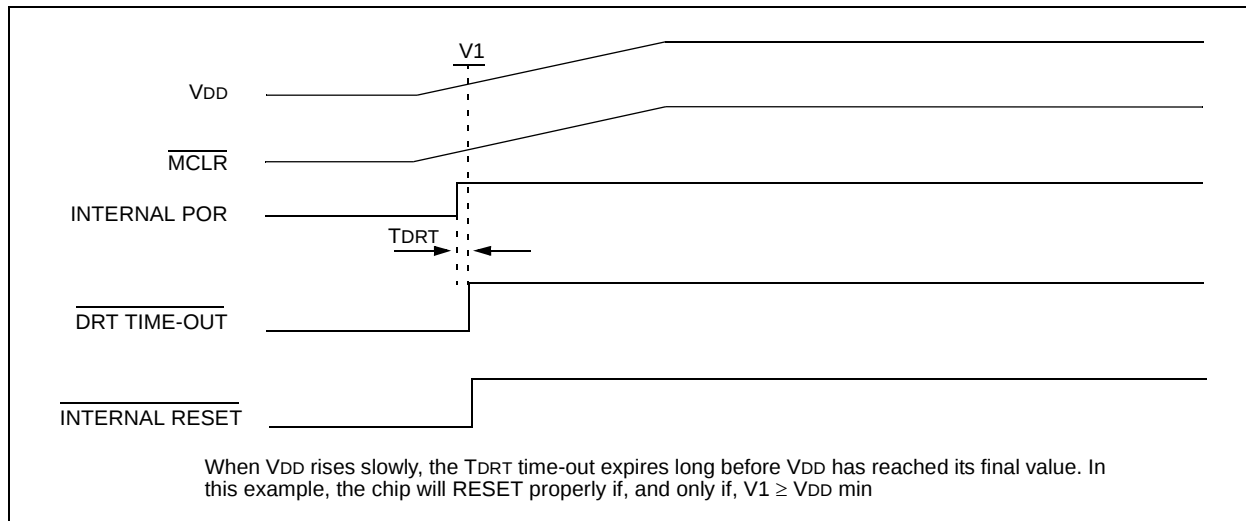


FIGURE 5-5: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ TIED TO VDD): SLOW VDD RISE TIME



5.2 Device Reset Timer (DRT)

The Device Reset Timer (DRT) provides an 18 ms nominal time-out on RESET regardless of Oscillator mode used. The DRT operates on an internal RC oscillator. The processor is kept in RESET as long as the DRT is active. The DRT delay allows V_{DD} to rise above V_{DD} min., and for the oscillator to stabilize.

Oscillator circuits based on crystals or ceramic resonators require a certain time after power-up to establish a stable oscillation. The on-chip DRT keeps the device in a RESET condition for approximately 18 ms after the voltage on the MCLR/V_{PP} pin has reached a logic high (V_{IH}) level. Thus, external RC networks connected to the MCLR input are not required in most cases, allowing for savings in cost-sensitive and/or space restricted applications.

The Device Reset time delay will vary from chip to chip due to V_{DD}, temperature, and process variation. See AC parameters for details.

The DRT will also be triggered upon a Watchdog Timer time-out. This is particularly important for applications using the WDT to wake the PIC16C5X from SLEEP mode automatically.

5.3 Reset on Brown-Out

A brown-out is a condition where device power (V_{DD}) dips below its minimum value, but not to zero, and then recovers. The device should be RESET in the event of a brown-out.

To RESET PIC16C5X devices when a brown-out occurs, external brown-out protection circuits may be built, as shown in Figure 5-6, Figure 5-7 and Figure 5-8.

FIGURE 5-6: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 1

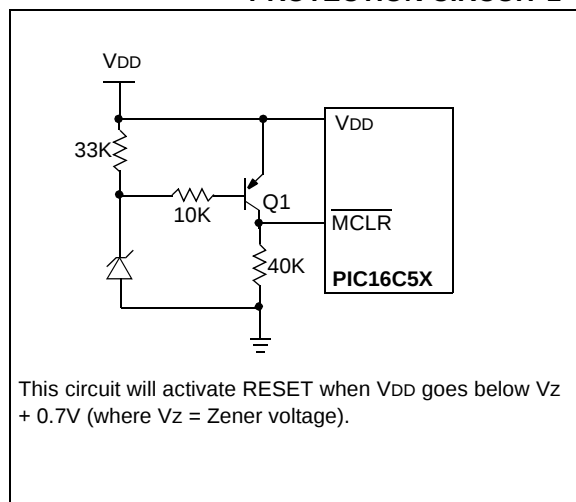


FIGURE 5-7: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 2

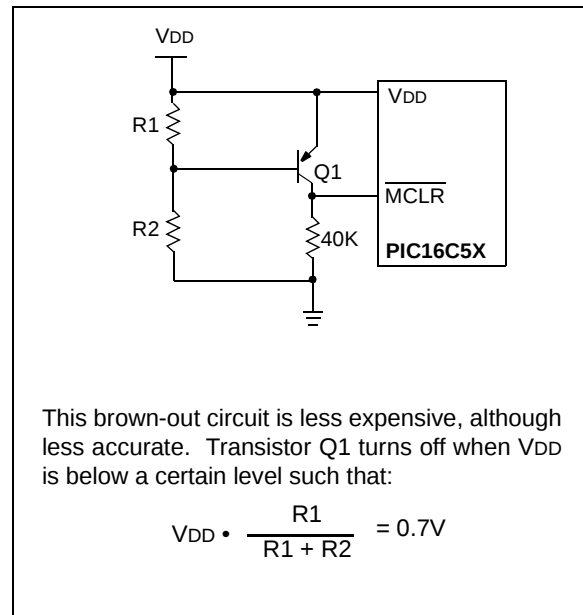


FIGURE 5-8: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 3

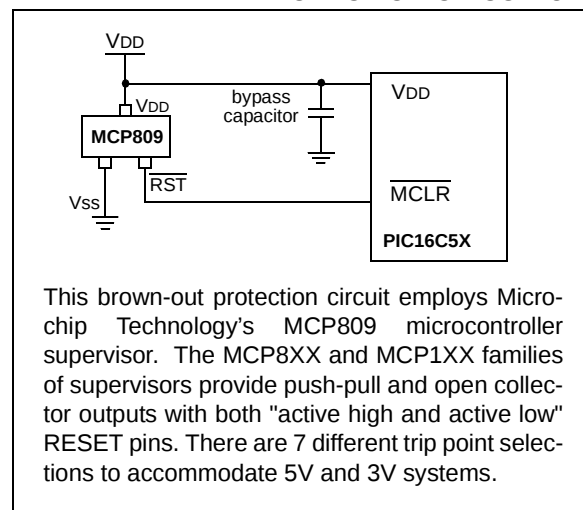


FIGURE 6-5: PIC16C57/CR57 REGISTER FILE MAP

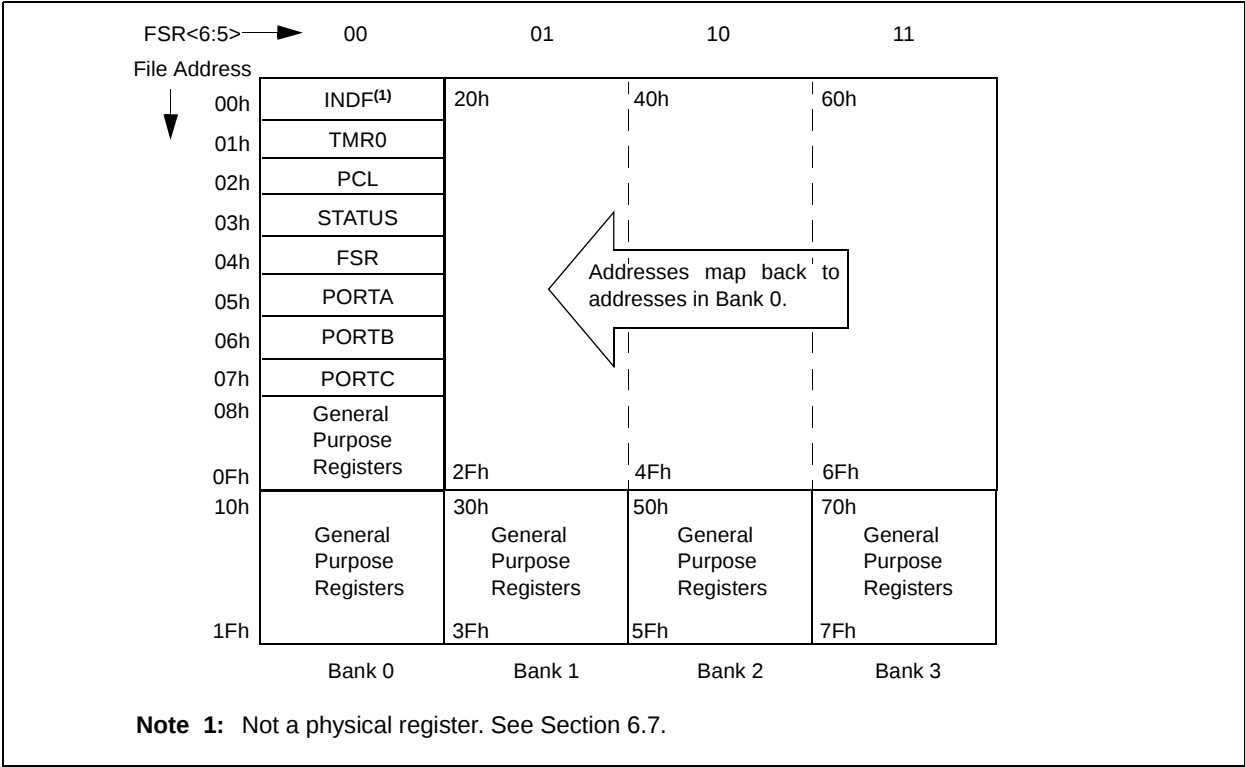
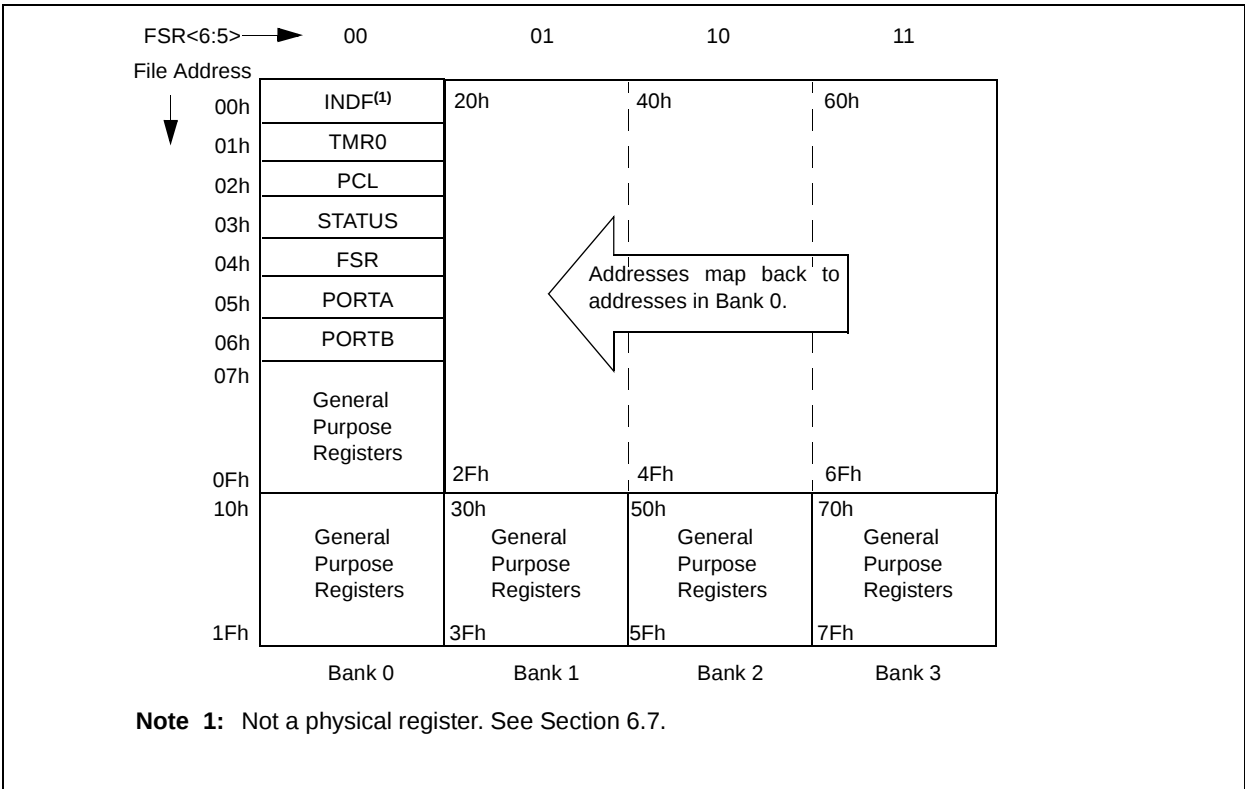


FIGURE 6-6: PIC16C58/CR58 REGISTER FILE MAP



PIC16C5X

6.2.2 SPECIAL FUNCTION REGISTERS

The Special Function Registers are registers used by the CPU and peripheral functions to control the operation of the device (Table 6-1).

The Special Registers can be classified into two sets. The Special Function Registers associated with the “core” functions are described in this section. Those related to the operation of the peripheral features are described in the section for each peripheral feature.

TABLE 6-1: SPECIAL FUNCTION REGISTER SUMMARY

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Details on Page
N/A	TRIS	I/O Control Registers (TRISA, TRISB, TRISC)								1111 1111	35
N/A	OPTION	Contains control bits to configure Timer0 and Timer0/WDT prescaler								--11 1111	30
00h	INDF	Uses contents of FSR to address data memory (not a physical register)								xxxx xxxx	32
01h	TMR0	Timer0 Module Register								xxxx xxxx	38
02h ⁽¹⁾	PCL	Low order 8 bits of PC								1111 1111	31
03h	STATUS	PA2	PA1	PA0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	29
04h	FSR	Indirect data memory address pointer								1xxx xxxx ⁽³⁾	32
05h	PORTA	—	—	—	—	RA3	RA2	RA1	RA0	---- xxxx	35
06h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx xxxx	35
07h ⁽²⁾	PORTC	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx xxxx	35

Legend: x = unknown, u = unchanged, — = unimplemented, read as '0' (if applicable). Shaded cells = unimplemented or unused

Note 1: The upper byte of the Program Counter is not directly accessible. See Section 6.5 for an explanation of how to access these bits.

2: File address 07h is a General Purpose Register on the PIC16C54, PIC16CR54, PIC16C56, PIC16CR56, PIC16C58 and PIC16CR58.

3: These values are valid for PIC16C57/CR57/C58/CR58. For the PIC16C54/CR54/C55/C56/CR56, the value on RESET is 111x xxxx and for $\overline{MCLR}$ and WDT Reset, the value is 111u uuuu.

8.1 Using Timer0 with an External Clock

When an external clock input is used for Timer0, it must meet certain requirements. The external clock requirement is due to internal phase clock (Tosc) synchronization. Also, there is a delay in the actual incrementing of Timer0 after synchronization.

8.1.1 EXTERNAL CLOCK SYNCHRONIZATION

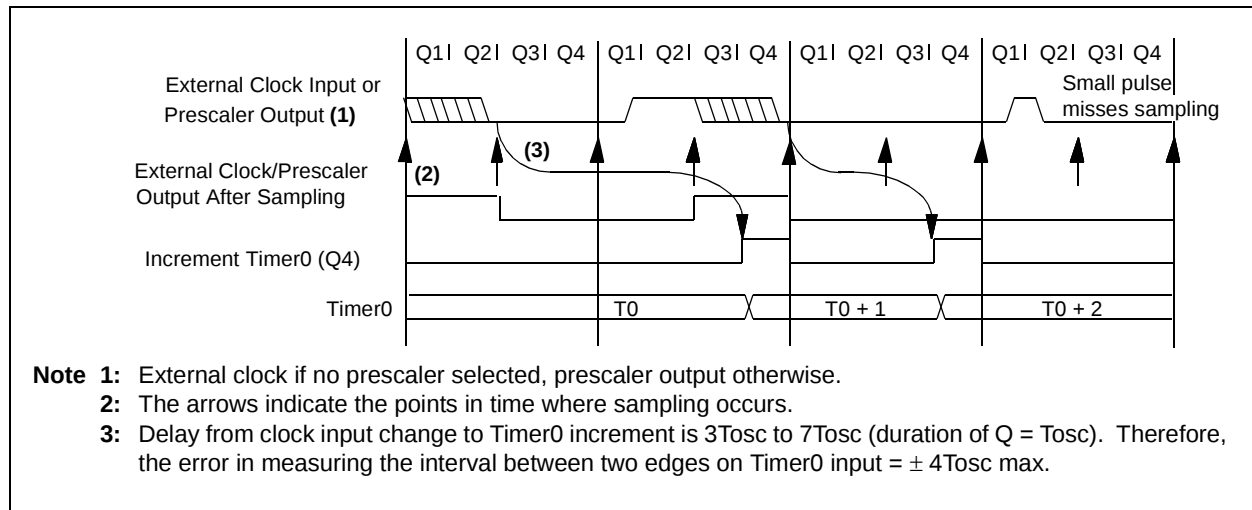
When no prescaler is used, the external clock input is the same as the prescaler output. The synchronization of T0CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks (Figure 8-5). Therefore, it is necessary for T0CKI to be high for at least 2Tosc (and a small RC delay of 20 ns) and low for at least 2Tosc (and a small RC delay of 20 ns). Refer to the electrical specification of the desired device.

When a prescaler is used, the external clock input is divided by the asynchronous ripple counter-type prescaler so that the prescaler output is symmetrical. For the external clock to meet the sampling requirement, the ripple counter must be taken into account. Therefore, it is necessary for T0CKI to have a period of at least 4Tosc (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on T0CKI high and low time is that they do not violate the minimum pulse width requirement of 10 ns. Refer to parameters 40, 41 and 42 in the electrical specification of the desired device.

8.1.2 TIMER0 INCREMENT DELAY

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time the Timer0 module is actually incremented. Figure 8-5 shows the delay from the external clock edge to the timer incrementing.

FIGURE 8-5: TIMER0 TIMING WITH EXTERNAL CLOCK



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9.2 Watchdog Timer (WDT)

The Watchdog Timer (WDT) is a free running on-chip RC oscillator which does not require any external components. This RC oscillator is separate from the RC oscillator of the OSC1/CLKIN pin. That means that the WDT will run even if the clock on the OSC1/CLKIN and OSC2/CLKOUT pins have been stopped, for example, by execution of a `SLEEP` instruction. During normal operation or `SLEEP`, a WDT Reset or Wake-up Reset generates a device RESET.

The $\overline{\text{TO}}$ bit (`STATUS<4>`) will be cleared upon a Watchdog Timer Reset (Section 6.3).

The WDT can be permanently disabled by programming the configuration bit `WDTE` as a '0' (Section 9.1). Refer to the PIC16C5X Programming Specifications (Literature Number DS30190) to determine how to access the configuration word.

9.2.1 WDT PERIOD

An 8-bit counter is available as a prescaler for the Timer0 module (Section 8.2), or as a postscaler for the Watchdog Timer (WDT), respectively. For simplicity, this counter is being referred to as "prescaler" throughout this data sheet. Note that the prescaler may be used by either the Timer0 module or the WDT, but not

both. Thus, a prescaler assignment for the Timer0 module means that there is no prescaler for the WDT, and vice-versa.

The `PSA` and `PS<2:0>` bits (`OPTION<3:0>`) determine prescaler assignment and prescale ratio (Section 6.4).

The WDT has a nominal time-out period of 18 ms (with no prescaler). If a longer time-out period is desired, a prescaler with a division ratio of up to 1:128 can be assigned to the WDT (under software control) by writing to the `OPTION` register. Thus, time-out a period of a nominal 2.3 seconds can be realized. These periods vary with temperature, V_{DD} and part-to-part process variations (see Device Characterization).

Under worst case conditions (V_{DD} = Min., Temperature = Max., WDT prescaler = 1:128), it may take several seconds before a WDT time-out occurs.

9.2.2 WDT PROGRAMMING CONSIDERATIONS

The `CLRWDT` instruction clears the WDT and the prescaler, if assigned to the WDT, and prevents it from timing out and generating a device RESET.

The `SLEEP` instruction RESETS the WDT and the prescaler, if assigned to the WDT. This gives the maximum `SLEEP` time before a WDT Wake-up Reset.

FIGURE 9-1: WATCHDOG TIMER BLOCK DIAGRAM

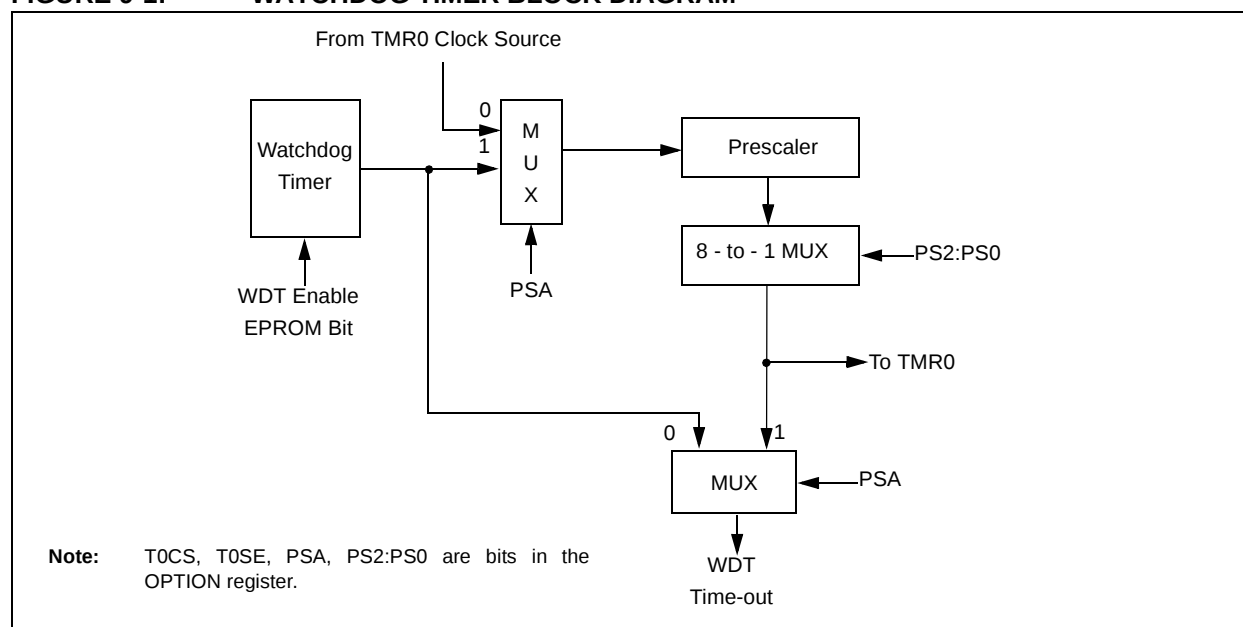


TABLE 9-1: SUMMARY OF REGISTERS ASSOCIATED WITH THE WATCHDOG TIMER

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-On Reset	Value on MCLR and WDT Reset
N/A	OPTION	—	—	Tosc	Tose	PSA	PS2	PS1	PS0	--11 1111	--11 1111

Legend: u = unchanged, - = unimplemented, read as '0'. Shaded cells not used by Watchdog Timer.

TABLE 11-1: DEVELOPMENT TOOLS FROM MICROCHIP

	PIC12CXXX	PIC14000	PIC16C5X	PIC16C6X	PIC16CXXX	PIC16F62X	PIC16C7X	PIC16C7XX	PIC16C8X	PIC16F8XX	PIC16C9XX	PIC17C4X	PIC17C7XX	PIC18CXX2	PIC18FXXX	24CXX/ 25CXX/ 93CXX	HCXXX	MCRFXXX	MCP2510
Software Tools	MPLAB® Integrated Development Environment	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓			
	MPLAB® C17 C Compiler											✓							
	MPLAB® C18 C Compiler													✓					
Emulators	MPASM™ Assembler/ MPLINK™ Object Linker	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓		
	MPLAB® ICE In-Circuit Emulator	✓	✓	✓	✓	✓**	✓	✓	✓	✓	✓	✓	✓	✓	✓				
	ICEPIC™ In-Circuit Emulator	✓	✓	✓	✓		✓	✓	✓		✓								
Debugger	MPLAB® ICD In-Circuit Debugger			✓*			✓*			✓					✓				
Programmers	PICSTART® Plus Entry Level Development Programmer	✓	✓	✓	✓	✓**	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓			
	PRO MATE® II Universal Device Programmer	✓	✓	✓	✓	✓**	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓		
Demo Boards and Eval Kits	PICDEM™ 1 Demonstration Board		✓				†		✓			✓							
	PICDEM™ 2 Demonstration Board				†		†							✓					
	PICDEM™ 3 Demonstration Board										✓								
	PICDEM™ 14A Demonstration Board		✓																
	PICDEM™ 17 Demonstration Board												✓						
	KEELOQ® Evaluation Kit																✓		
	KEELOQ® Transponder Kit																✓		
	microID™ Programmer's Kit																	✓	
	125 kHz microID™ Developer's Kit																	✓	
	125 kHz Anticollision Developer's Kit																	✓	
	13.56 MHz Anticollision microID™ Developer's Kit																	✓	
	MCP2510 CAN Developer's Kit																	✓	✓

* Contact the Microchip Technology Inc. web site at www.microchip.com for information on how to use the MPLAB® ICD In-Circuit Debugger (DV164001) with PIC16C62, 63, 64, 65, 72, 73, 74, 76, 77.

** Contact Microchip Technology Inc. for availability date.

† Development tool is available on select devices.

PIC16C5X

NOTES:

PIC16C5X

12.3 DC Characteristics: PIC16C54/55/56/57-RCE, XTE, 10E, HSE, LPE (Extended)

PIC16C54/55/56/57-RCE, XTE, 10E, HSE, LPE (Extended)			Standard Operating Conditions (unless otherwise specified) Operating Temperature $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
Param No.	Symbol	Characteristic/Device	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage PIC16C5X-RCE PIC16C5X-XTE PIC16C5X-10E PIC16C5X-HSE PIC16C5X-LPE	3.25 3.25 4.5 4.5 2.5	— — — — —	6.0 6.0 5.5 5.5 6.0	V V V V V	
D002	VDR	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD Start Voltage to ensure Power-on Reset	—	VSS	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset
D010	IDD	Supply Current ⁽²⁾ PIC16C5X-RCE ⁽³⁾ PIC16C5X-XTE PIC16C5X-10E PIC16C5X-HSE PIC16C5X-HSE PIC16C5X-LPE	— — — — — —	1.8 1.8 4.8 4.8 9.0 19	3.3 3.3 10 10 20 55	mA mA mA mA mA μA	FOSC = 4 MHz, VDD = 5.5V FOSC = 4 MHz, VDD = 5.5V FOSC = 10 MHz, VDD = 5.5V FOSC = 10 MHz, VDD = 5.5V FOSC = 16 MHz, VDD = 5.5V FOSC = 32 kHz, VDD = 3.25V, WDT disabled
D020	IPD	Power-down Current ⁽²⁾	— —	5.0 0.8	22 18	μA μA	VDD = 3.25V, WDT enabled VDD = 3.25V, WDT disabled

* These parameters are characterized but not tested.

† Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

- Note 1:** This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
- 2:** The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
- a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.
- b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
- 3:** Does not include current through REXT. The current through the resistor can be estimated by the formula: $I_R = V_{DD}/2R_{EXT}$ (mA) with REXT in k Ω .

12.6 Timing Parameter Symbolology and Load Conditions

The timing parameter symbols have been created with one of the following formats:

- 1. TppS2ppS
- 2. TppS

T		T
F	Frequency	Time

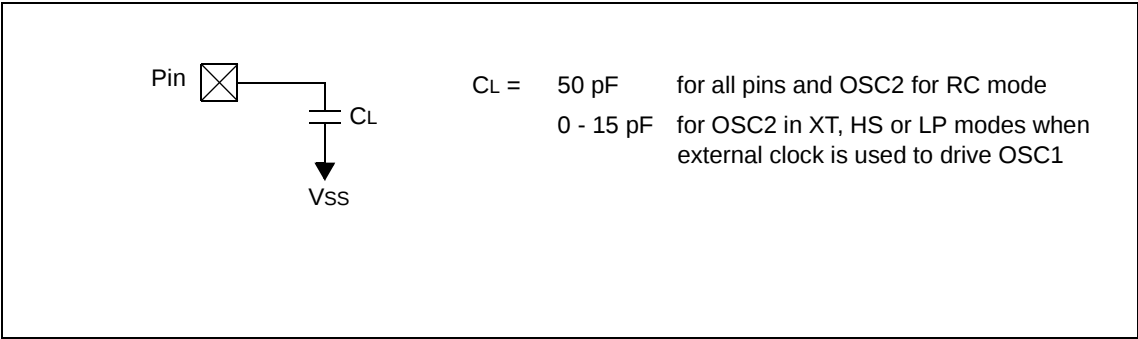
Lowercase letters (pp) and their meanings:

pp		
2	to	mc $\overline{\text{MCLR}}$
ck	CLKOUT	osc oscillator
cy	cycle time	os OSC1
drt	device reset timer	t0 T0CKI
io	I/O port	wdt watchdog timer

Uppercase letters and their meanings:

S		
F	Fall	P Period
H	High	R Rise
I	Invalid (Hi-impedance)	V Valid
L	Low	Z Hi-impedance

FIGURE 12-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS - PIC16C54/55/56/57



PIC16C5X

FIGURE 14-11: V_{TH} (INPUT THRESHOLD VOLTAGE) OF OSC1 INPUT (XT, HS, AND LP MODES) vs. V_{DD}

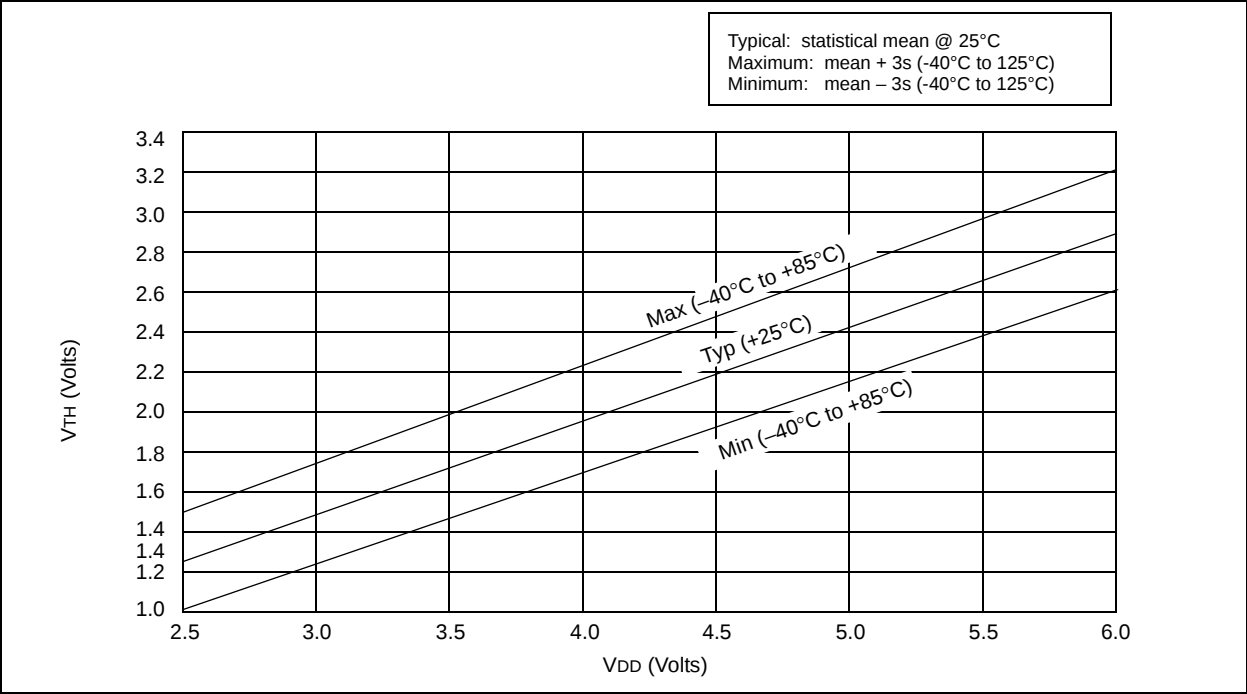
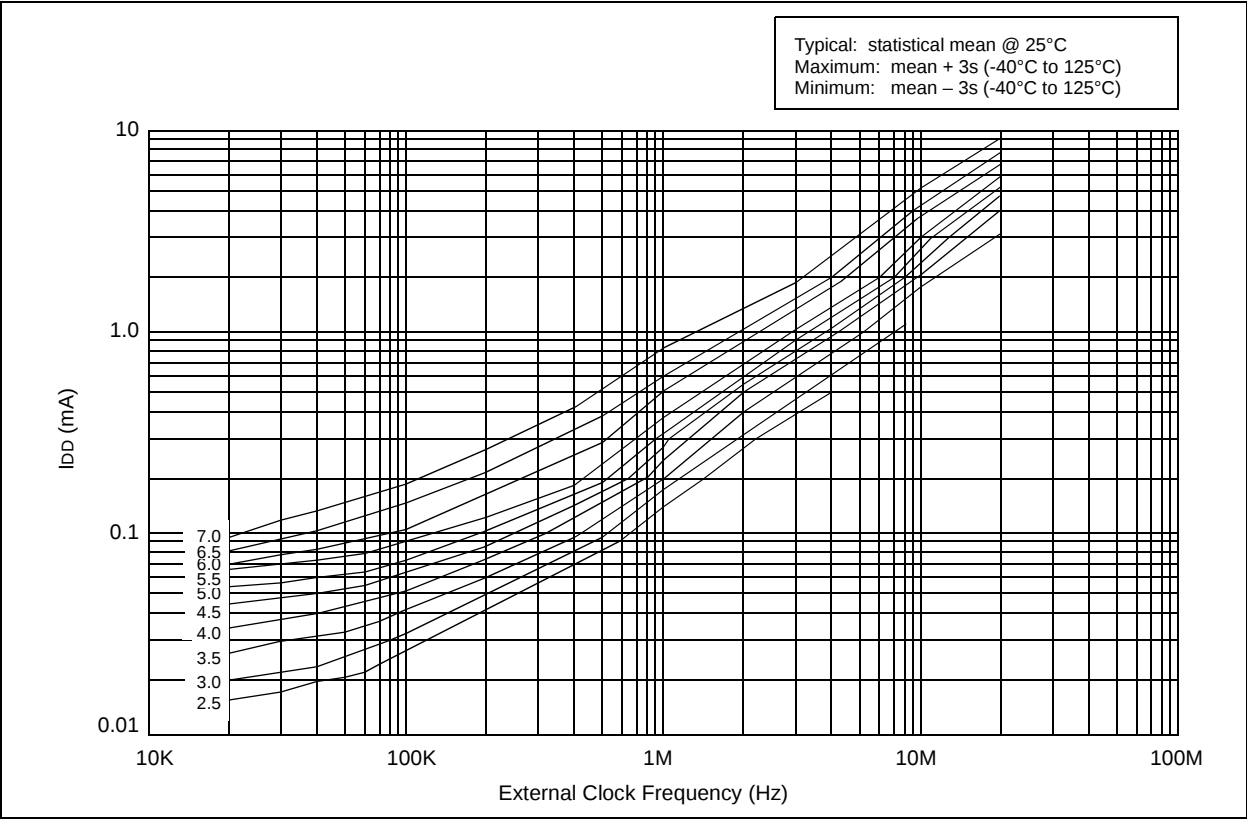


FIGURE 14-12: TYPICAL I_{DD} VS. FREQUENCY (EXTERNAL CLOCK, 25°C)



PIC16C5X

FIGURE 16-5: TYPICAL I_{PD} vs. V_{DD}, WATCHDOG DISABLED (25°C)

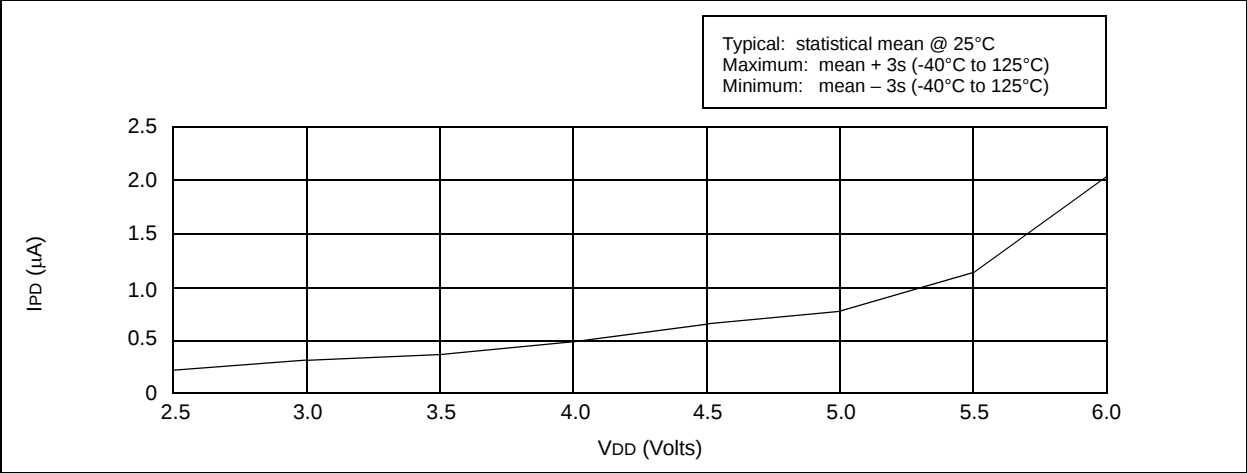
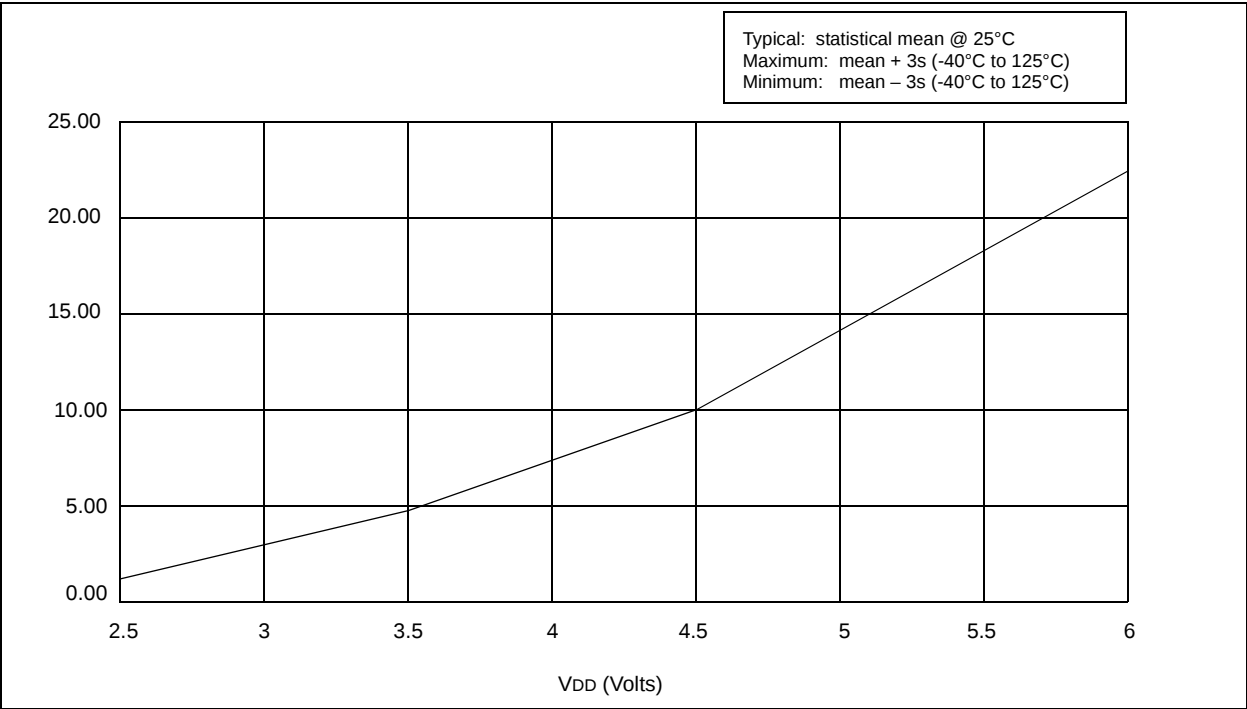


FIGURE 16-6: TYPICAL I_{PD} vs. V_{DD}, WATCHDOG ENABLED (25°C)



PIC16C5X

FIGURE 18-6: TYPICAL I_{PD} vs. V_{DD} , WATCHDOG ENABLED (25°C)

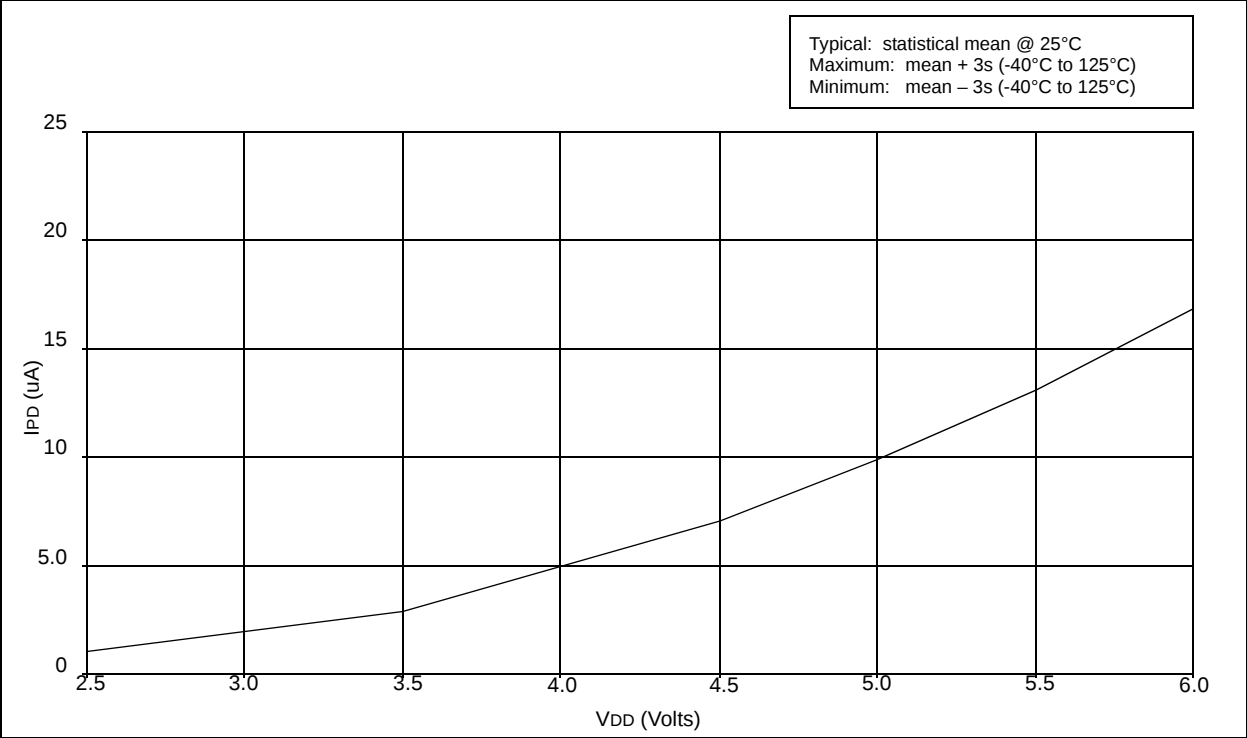


FIGURE 18-7: TYPICAL I_{PD} vs. V_{DD} , WATCHDOG ENABLED (-40°C, 85°C)

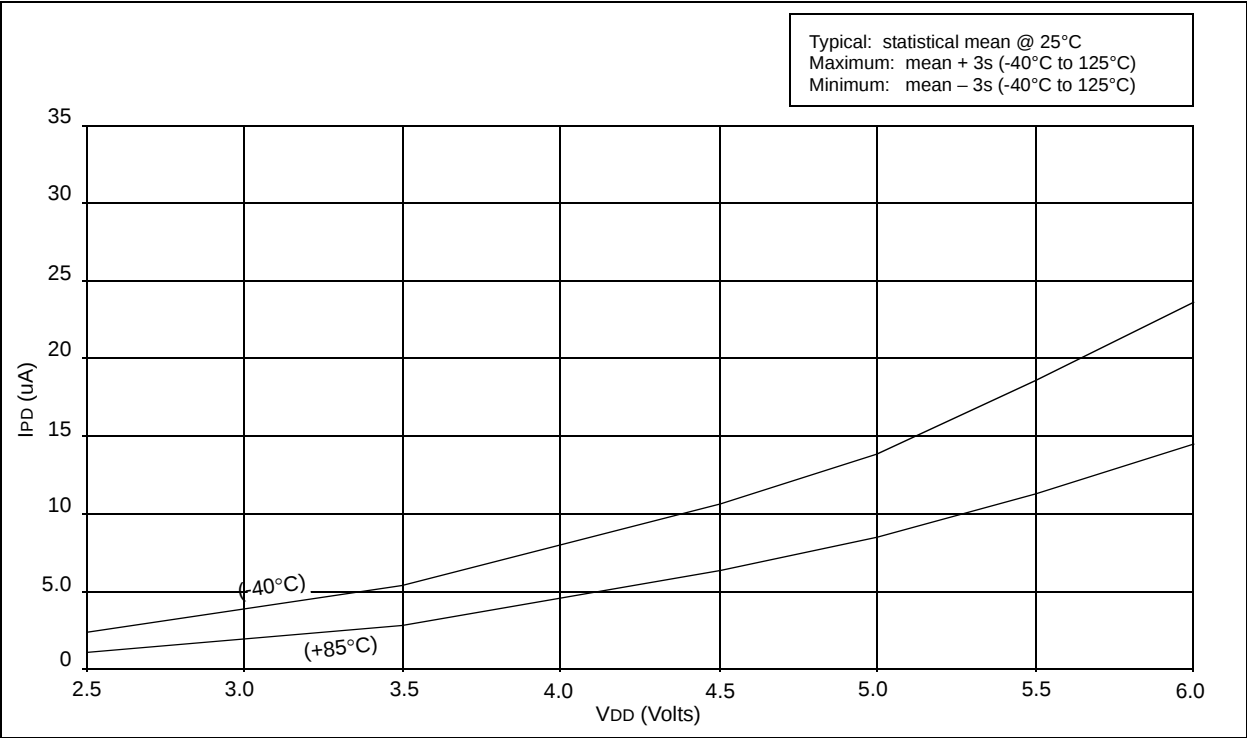


FIGURE 18-14: WDT TIMER TIME-OUT PERIOD vs. VDD⁽¹⁾

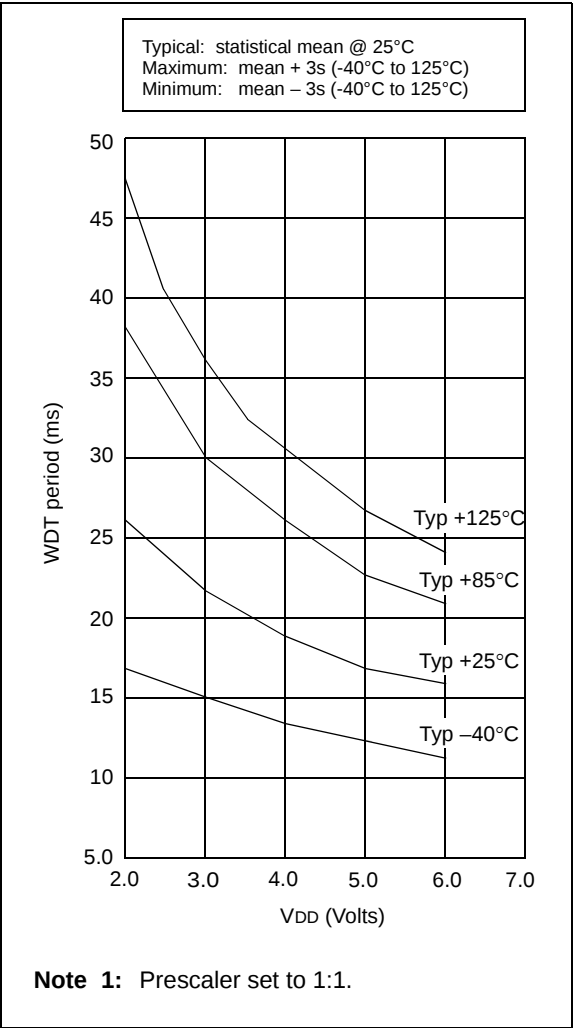


FIGURE 18-15: PORTA, B AND C I_{OH} vs. V_{OH}, VDD = 3 V

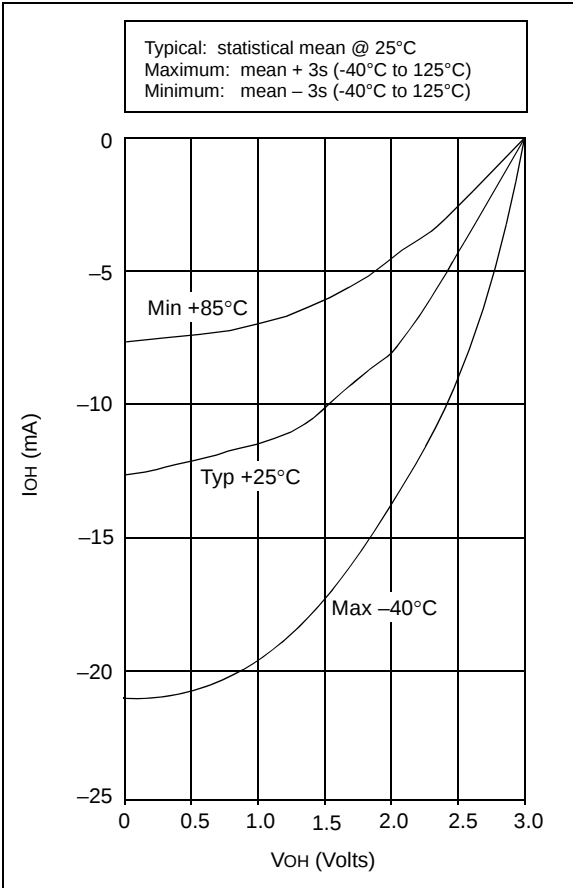


FIGURE 18-16: PORTA, B AND C I_{OH} vs. V_{OH}, V_{DD} = 5 V

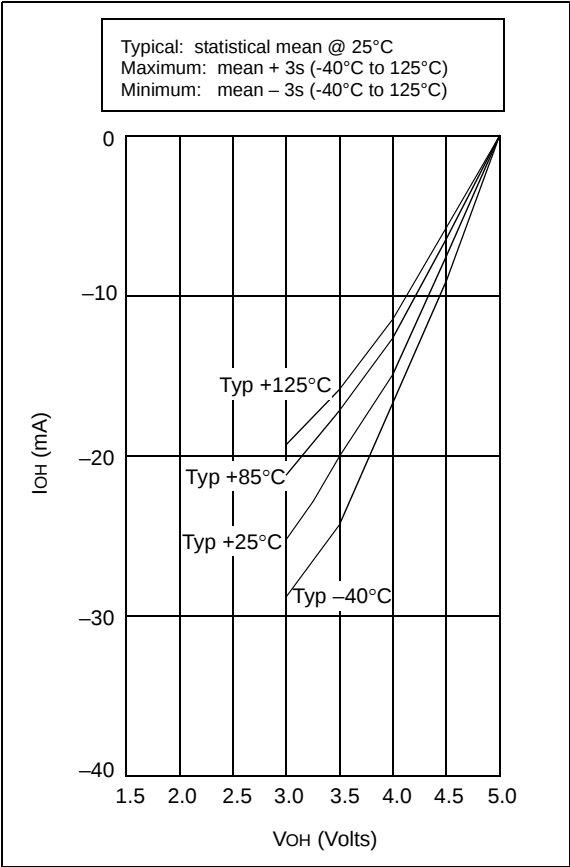
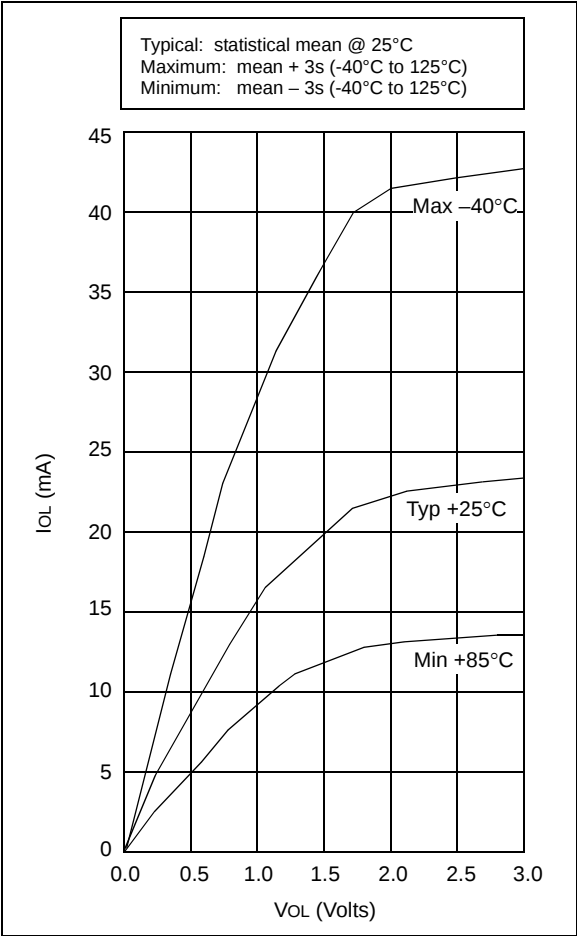


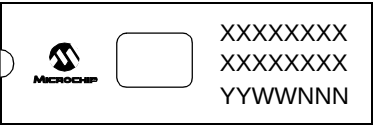
FIGURE 18-17: PORTA, B AND C I_{OL} vs. V_{OL}, V_{DD} = 3 V



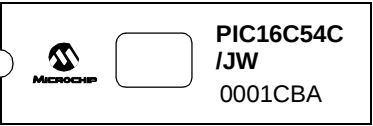
PIC16C5X

Package Marking Information (Cont'd)

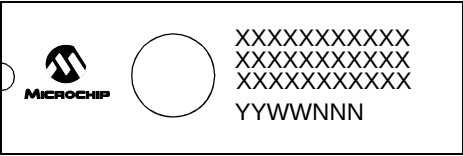
18-Lead CERDIP Windowed



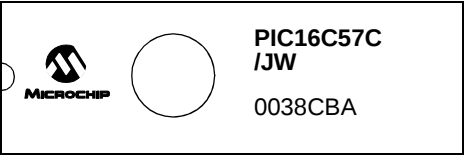
Example



28-Lead CERDIP Windowed



Example

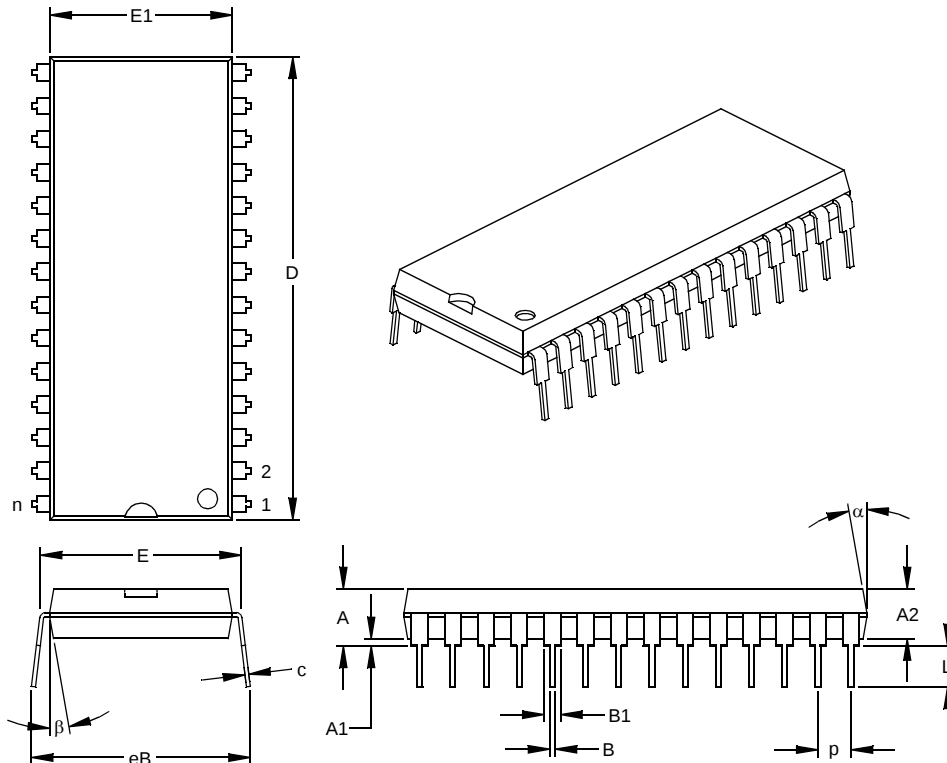


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

28-Lead Plastic Dual In-line (P) – 600 mil (PDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.160	.175	.190	4.06	4.45	4.83
Molded Package Thickness	A2	.140	.150	.160	3.56	3.81	4.06
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.595	.600	.625	15.11	15.24	15.88
Molded Package Width	E1	.505	.545	.560	12.83	13.84	14.22
Overall Length	D	1.395	1.430	1.465	35.43	36.32	37.21
Tip to Seating Plane	L	.120	.130	.135	3.05	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.030	.050	.070	0.76	1.27	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing	§	.620	.650	.680	15.75	16.51	17.27
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MO-011

Drawing No. C04-079

ON-LINE SUPPORT

Microchip provides on-line support on the Microchip World Wide Web (WWW) site.

The web site is used by Microchip as a means to make files and information easily available to customers. To view the site, the user must have access to the Internet and a web browser, such as Netscape or Microsoft Explorer. Files are also available for FTP download from our FTP site.

Connecting to the Microchip Internet Web Site

The Microchip web site is available by using your favorite Internet browser to attach to:

www.microchip.com

The file transfer site is available by using an FTP service to connect to:

<ftp://ftp.microchip.com>

The web site and file transfer site provide a variety of services. Users may download files for the latest Development Tools, Data Sheets, Application Notes, User's Guides, Articles and Sample Programs. A variety of Microchip specific business information is also available, including listings of Microchip sales offices, distributors and factory representatives. Other data available for consideration is:

- Latest Microchip Press Releases
- Technical Support Section with Frequently Asked Questions
- Design Tips
- Device Errata
- Job Postings
- Microchip Consultant Program Member Listing
- Links to other useful web sites related to Microchip Products
- Conferences for products, Development Systems, technical information and more
- Listing of seminars and events

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	-	XX	X	/XX	XXX
Device		Frequency Range/OSC Type	Temperature Range	Package	Pattern
Device		PIC16C54 PIC16C54A PIC16CR54A PIC16C54C PIC16CR54C PIC16C55 PIC16C55A PIC16C56 PIC16C56A PIC16CR56A PIC16C57 PIC16C57C PIC16CR57C PIC16C58B PIC16CR58B	PIC16C54T ⁽²⁾ PIC16C54AT ⁽²⁾ PIC16CR54AT ⁽²⁾ PIC16C54CT ⁽²⁾ PIC16CR54CT ⁽²⁾ PIC16C55T ⁽²⁾ PIC16C55AT ⁽²⁾ PIC16C56T ⁽²⁾ PIC16C56AT ⁽²⁾ PIC16CR56AT ⁽²⁾ PIC16C57T ⁽²⁾ PIC16C57CT ⁽²⁾ PIC16CR57CT ⁽²⁾ PIC16C58BT ⁽²⁾ PIC16CR58BT ⁽²⁾		
Frequency Range/ Oscillator Type		RC Resistor Capacitor LP Low Power Crystal XT Standard Crystal/Resonator HS High Speed Crystal 02 200 KHz (LP) or 2 MHz (XT and RC) 04 200 KHz (LP) or 4 MHz (XT and RC) 10 10 MHz (HS only) 20 20 MHz (HS only) 40 40 MHz (HS only) b ⁽⁴⁾ No oscillator type for JW packages ⁽³⁾			
		*RC/LP/XT/HS are for 16C54/55/56/57 devices only -02 is available for 16LV54A only -04/10/20 options are available for all other devices -40 is available for 16C54C/55A/56A/57C/58B devices only			
Temperature Range		b ⁽⁴⁾ = 0°C to +70°C I = -40°C to +85°C E = -40°C to +125°C			
Package		S = Die in Waffle Pack JW = 28-pin 600 mil/18-pin 300 mil windowed CER-DIP ⁽³⁾ P = 28-pin 600 mil/18-pin 300 mil PDIP SO = 300 mil SOIC SS = 209 mil SSOP SP = 28-pin 300 mil Skinny PDIP			
		*See Section 21 for additional package information.			
Pattern		QTP, SQTP, ROM code (factory specified) or Special Requirements. Blank for OTP and Windowed devices.			

Examples:

- PIC16C55A - 04/P 301 = Commercial Temp., PDIP package, 4 MHz, standard V_{DD} limits, QTP pattern #301
- PIC16LC54C - 04I/SO Industrial Temp., SOIC package, 200 kHz, extended V_{DD} limits
- PIC16C57 - RC/SP = RC Oscillator, commercial temp, skinny PDIP package, 4 MHz, standard V_{DD} limits
- PIC16C58BT -40/SS 123 = commercial temp, SSOP package in tape and reel, 4 MHz, extended V_{DD} limits, ROM pattern #123

- Note 1:** C = normal voltage range
LC = extended
- 2:** T = in tape and reel - SOIC and SSOP packages only
- 3:** JW Devices are UV erasable and can be programmed to any device configuration. JW Devices meet the electrical requirements of each oscillator type, including LC devices.
- 4:** b = Blank

Sales and Support

Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

- Your local Microchip sales office
- The Microchip Worldwide Site (www.microchip.com)